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What if a partnership with SCHOTT enables the future of chip packaging?

Content

1. Executive summary . . . 3

2. From glass interest to manufacturing readiness . . . 4

3. Why glass adoption is not a drop-in transition . . . 5

4. From application need to qualification . . . 6

5. Beyond the material: engineering glass for the customer application . . . 7

6. From material to manufacturing . . . 8

7. Partnership across the value chain . . . 9

8. Conclusion . . . 10

References . . . 10

1. Executive summary

Glass is gaining attention in advanced semiconductor manufacturing because it can support demanding package architectures as well as the precision processes required to build them. With the industry moving from early evaluation toward practical adoption, the central question is changing. The issue is no longer only whether glass has attractive material properties. It is how those properties can be translated into qualified, repeatable, and scalable manufacturing flows. [1,2]

That shift matters because glass is not a drop-in material. Its value depends on how well the glass composition, format, surface condition, and manufacturing quality match the customer's application. Different glass-based solutions each create different requirements. In every case, customers need more than a promising sample. They need a path towards qualification. [2,3]

Moving from technical interest to manufacturing confidence requires matching the glass solution to the application, validating it through meaningful qualification steps, understanding its behavior during further processing, ensuring consistent production quality, and aligning material decisions with the broader semiconductor ecosystem.

For SCHOTT, this is where specialty-glass expertise becomes a partnership model. With deep experience in engineered glass, application support, controlled production, and ongoing work in advanced packaging, SCHOTT helps customers connect material potential with manufacturing reality.

2. From glass interest to manufacturing readiness

Glass has become part of the advanced packaging conversation because the industry is asking more from the materials behind semiconductor manufacturing. As packages become more complex and process tolerances tighten, the material platform can influence whether an architecture is not only technically attractive, but manufacturable. [1,2]

Stakeholders across the semiconductor value chain are therefore moving from general interest in glass toward more practical questions of adoption. Early discussions often focus on potential applications and technology concepts. As evaluation programs progress, however, the focus shifts to implementation: how a glass solution can be tested, integrated into process flows, qualified for production, and supplied with the consistency required for semiconductor manufacturing. [1,5,7,9]

That transition changes the decision-making process. Packaging engineers need evidence that the material can fit the intended process flow. Manufacturing teams need confidence that it can be handled, processed, inspected, and integrated without introducing uncontrolled variability. Purchasing organizations focus on stable quality and reliable availability, while business development and OEM stakeholders look for a credible path from technology interest to roadmap relevance.

Glass adoption is therefore an industrialization question. Material potential is necessary, but not sufficient. A glass solution must be translated into specifications, samples, test vehicles, process assumptions, quality controls, and supply conditions that make sense for the customer's environment.

The strategic challenge is not simply to introduce glass into the semiconductor value chain, but to create the conditions for reliable adoption. That requires a supplier relationship that begins early enough to shape the qualification path and is technical enough to support the customer as requirements become more specific.

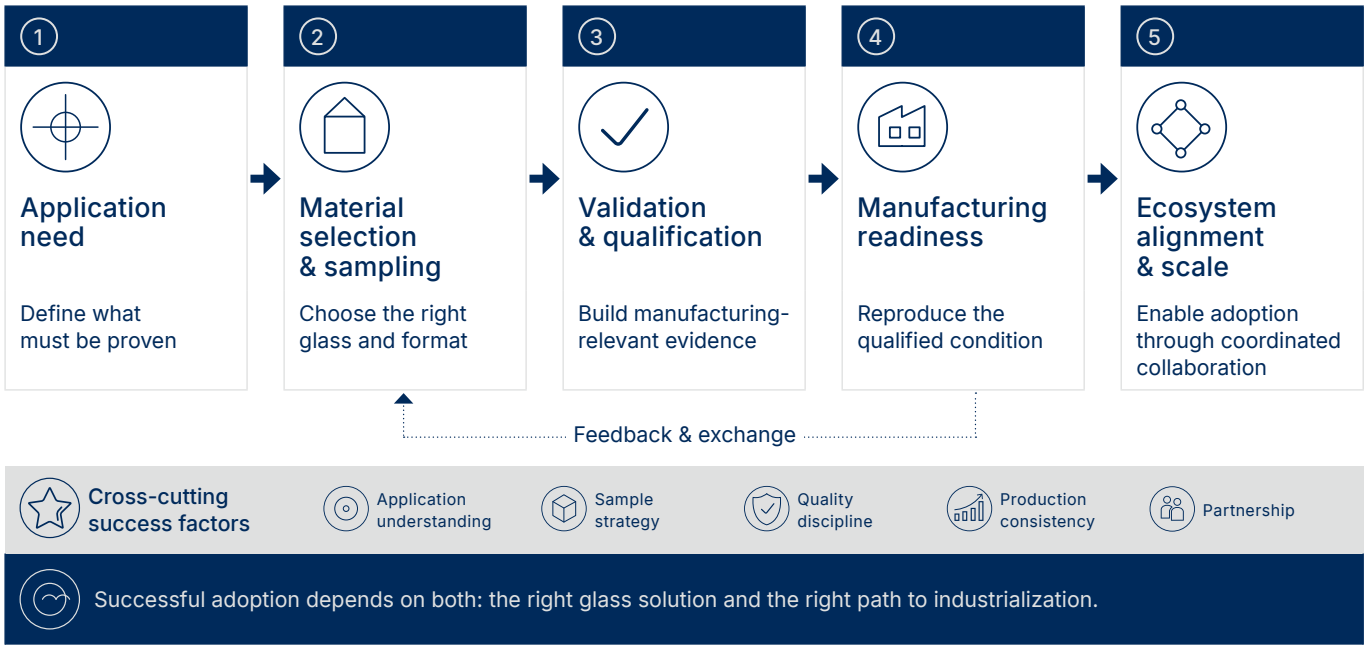

Figure 1. From technical interest to manufacturing confidence
Glass adoption follows an iterative path from early evaluation to manufacturing-ready implementation.

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